

L Number	Hits	Search Text	DB	Time stamp
-	27	etch\$3 same (interlayer interlevel intermediate) same (organic teflon polyaryyl\$6 poly\$1para\$1xylene) same (NH3 "NH.sub.3" ammonia)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/14 12:23
-	2300	etch\$3 and (interlayer interlevel intermediate) and (organic teflon polyaryyl\$6 poly\$1para\$1xylene) and (NH3 "NH.sub.3" ammonia) and (plasma merie RIE dry adj etch\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/14 13:02
-	613	((etch\$3 and (interlayer interlevel intermediate) and (organic teflon polyaryyl\$6 poly\$1para\$1xylene) and (NH3 "NH.sub.3" ammonia) and (plasma merie RIE dry adj etch\$3)) and ((interlayer interlevel intermediate) near insulat\$3) not (etch\$3 same (interlayer interlevel intermediate) same (organic teflon polyaryyl\$6 poly\$1para\$1xylene) same (NH3 "NH.sub.3" ammonia))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/14 12:22
-	350	((etch\$3 and (interlayer interlevel intermediate) and (organic teflon polyaryyl\$6 poly\$1para\$1xylene) and (NH3 "NH.sub.3" ammonia) and (plasma merie RIE dry adj etch\$3)) and ((interlayer interlevel intermediate) near dielectric) not (etch\$3 same (interlayer interlevel intermediate) same (organic teflon polyaryyl\$6 poly\$1para\$1xylene) same (NH3 "NH.sub.3" ammonia))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/14 12:22
-	925	((etch\$3 and (interlayer interlevel intermediate) and (organic teflon polyaryyl\$6 poly\$1para\$1xylene) and (NH3 "NH.sub.3" ammonia) and (plasma merie RIE dry adj etch\$3)) and ((interlayer interlevel intermediate) near insulat\$3) not (etch\$3 same (interlayer interlevel intermediate) same (organic teflon polyaryyl\$6 poly\$1para\$1xylene) same (NH3 "NH.sub.3" ammonia))) ((etch\$3 and (interlayer interlevel intermediate) and (organic teflon polyaryyl\$6 poly\$1para\$1xylene) and (NH3 "NH.sub.3" ammonia) and (plasma merie RIE dry adj etch\$3)) and ((interlayer interlevel intermediate) near dielectric) not (etch\$3 same (interlayer interlevel intermediate) same (organic teflon polyaryyl\$6 poly\$1para\$1xylene) same (NH3 "NH.sub.3" ammonia)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/14 12:23
-	289	((((etch\$3 and (interlayer interlevel intermediate) and (organic teflon polyaryyl\$6 poly\$1para\$1xylene) and (NH3 "NH.sub.3" ammonia) and (plasma merie RIE dry adj etch\$3)) and ((interlayer interlevel intermediate) near insulat\$3) not (etch\$3 same (interlayer interlevel intermediate) same (organic teflon polyaryyl\$6 poly\$1para\$1xylene) same (NH3 "NH.sub.3" ammonia))) ((etch\$3 and (interlayer interlevel intermediate) and (organic teflon polyaryyl\$6 poly\$1para\$1xylene) and (NH3 "NH.sub.3" ammonia) and (plasma merie RIE dry adj etch\$3)) and ((interlayer interlevel intermediate) near dielectric) not (etch\$3 same (interlayer interlevel intermediate) same (organic teflon polyaryyl\$6 poly\$1para\$1xylene) same (NH3 "NH.sub.3" ammonia)))) and etch\$3 same (NH3 "NH.sub.3" ammonia)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/14 12:23

-	184	(((etch\$3 and (interlayer interlevel intermediate) and (organic teflon polyaryl\$6 poly\$1para\$1xylene) and (NH3 "NH.sub.3" ammonia) and (plasma merie RIE dry adj etch\$3)) and ((interlayer interlevel intermediate) near insulat\$3) not (etch\$3 same (interlayer interlevel intermediate) same (organic teflon polyaryl\$6 poly\$1para\$1xylene) same (NH3 "NH.sub.3" ammonia))) ((etch\$3 and (interlayer interlevel intermediate) and (organic teflon polyaryl\$6 poly\$1para\$1xylene) and (NH3 "NH.sub.3" ammonia) and (plasma merie RIE dry adj etch\$3)) and ((interlayer interlevel intermediate) near dielectric) not (etch\$3 same (interlayer interlevel intermediate) same (organic teflon polyaryl\$6 poly\$1para\$1xylene) same (NH3 "NH.sub.3" ammonia))) and etch\$3 same (NH3 "NH.sub.3" ammonia)) and etch\$3 with (NH3 "NH.sub.3" ammonia)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/14 12:23
-	37	(((etch\$3 and (interlayer interlevel intermediate) and (organic teflon polyaryl\$6 poly\$1para\$1xylene) and (NH3 "NH.sub.3" ammonia) and (plasma merie RIE dry adj etch\$3)) and ((interlayer interlevel intermediate) near insulat\$3) not (etch\$3 same (interlayer interlevel intermediate) same (organic teflon polyaryl\$6 poly\$1para\$1xylene) same (NH3 "NH.sub.3" ammonia))) ((etch\$3 and (interlayer interlevel intermediate) and (organic teflon polyaryl\$6 poly\$1para\$1xylene) and (NH3 "NH.sub.3" ammonia) and (plasma merie RIE dry adj etch\$3)) and ((interlayer interlevel intermediate) near dielectric) not (etch\$3 same (interlayer interlevel intermediate) same (organic teflon polyaryl\$6 poly\$1para\$1xylene) same (NH3 "NH.sub.3" ammonia))) and etch\$3 same (NH3 "NH.sub.3" ammonia)) and etch\$3 with (NH3 "NH.sub.3" ammonia)) and (interlayer interlevel intermediate) with (organic teflon polyaryl\$6 poly\$1para\$1xylene)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/14 12:24
-	780	(etch\$3 and (interlayer interlevel intermediate) and (organic teflon polyaryl\$6 poly\$1para\$1xylene) and (NH3 "NH.sub.3" ammonia) and (plasma merie RIE dry adj etch\$3)) and (NH3 "NH.sub.3" ammonia) same (plasma merie RIE dry adj etch\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/14 13:03
-	430	(((etch\$3 and (interlayer interlevel intermediate) and (organic teflon polyaryl\$6 poly\$1para\$1xylene) and (NH3 "NH.sub.3" ammonia) and (plasma merie RIE dry adj etch\$3)) and ((interlayer interlevel intermediate) near insulat\$3) not (etch\$3 same (interlayer interlevel intermediate) same (organic teflon polyaryl\$6 poly\$1para\$1xylene) same (NH3 "NH.sub.3" ammonia))) ((etch\$3 and (interlayer interlevel intermediate) and (organic teflon polyaryl\$6 poly\$1para\$1xylene) and (NH3 "NH.sub.3" ammonia) and (plasma merie RIE dry adj etch\$3)) and ((interlayer interlevel intermediate) near dielectric) not (etch\$3 same (interlayer interlevel intermediate) same (organic teflon polyaryl\$6 poly\$1para\$1xylene) same (NH3 "NH.sub.3" ammonia))) and (NH3 "NH.sub.3" ammonia) same (plasma merie RIE dry adj etch\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/14 13:04

-	313	((etch\$3 and (interlayer interlevel intermediate) and (organic teflon polyaryl\$6 poly\$1para\$1xylene) and (NH3 "NH.sub.3" ammonia) and (plasma merie RIE dry adj etch\$3)) and ((interlayer interlevel intermediate) near insulat\$3) not (etch\$3 same (interlayer interlevel intermediate) same (organic teflon polyaryl\$6 poly\$1para\$1xylene) same (NH3 "NH.sub.3" ammonia))) ((etch\$3 and (interlayer interlevel intermediate) and (organic teflon polyaryl\$6 poly\$1para\$1xylene) and (NH3 "NH.sub.3" ammonia) and (plasma merie RIE dry adj etch\$3)) and ((interlayer interlevel intermediate) near dielectric) not (etch\$3 same (interlayer interlevel intermediate) same (organic teflon polyaryl\$6 poly\$1para\$1xylene) same (NH3 "NH.sub.3" ammonia)))) and (NH3 "NH.sub.3" ammonia) with (plasma merie RIE dry adj etch\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/14 13:05
-	63	(((((etch\$3 and (interlayer interlevel intermediate) and (organic teflon polyaryl\$6 poly\$1para\$1xylene) and (NH3 "NH.sub.3" ammonia) and (plasma merie RIE dry adj etch\$3)) and ((interlayer interlevel intermediate) near insulat\$3) not (etch\$3 same (interlayer interlevel intermediate) same (organic teflon polyaryl\$6 poly\$1para\$1xylene) same (NH3 "NH.sub.3" ammonia))) ((etch\$3 and (interlayer interlevel intermediate) and (organic teflon polyaryl\$6 poly\$1para\$1xylene) and (NH3 "NH.sub.3" ammonia) and (plasma merie RIE dry adj etch\$3)) and ((interlayer interlevel intermediate) near dielectric) not (etch\$3 same (interlayer interlevel intermediate) same (organic teflon polyaryl\$6 poly\$1para\$1xylene) same (NH3 "NH.sub.3" ammonia)))) and etch\$3 same (NH3 "NH.sub.3" ammonia)) and etch\$3 with (NH3 "NH.sub.3" ammonia)) and (((etch\$3 and (interlayer interlevel intermediate) and (organic teflon polyaryl\$6 poly\$1para\$1xylene) and (NH3 "NH.sub.3" ammonia) and (plasma merie RIE dry adj etch\$3)) and ((interlayer interlevel intermediate) near insulat\$3) not (etch\$3 same (interlayer interlevel intermediate) same (organic teflon polyaryl\$6 poly\$1para\$1xylene) same (NH3 "NH.sub.3" ammonia))) ((etch\$3 and (interlayer interlevel intermediate) and (organic teflon polyaryl\$6 poly\$1para\$1xylene) and (NH3 "NH.sub.3" ammonia) and (plasma merie RIE dry adj etch\$3)) and ((interlayer interlevel intermediate) near dielectric) not (etch\$3 same (interlayer interlevel intermediate) same (organic teflon polyaryl\$6 poly\$1para\$1xylene) same (NH3 "NH.sub.3" ammonia)))) and (NH3 "NH.sub.3" ammonia) with (plasma merie RIE dry adj etch\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/14 13:05

	43	<p>((((etch\$3 and (interlayer interlevel intermediate) and (organic teflon polyaryl\$6 poly\$1para\$1xylene) and (NH3 "NH.sub.3" ammonia) and (plasma merie RIE dry adj etch\$3)) and ((interlayer interlevel intermediate) near insulat\$3) not (etch\$3 same (interlayer interlevel intermediate) same (organic teflon polyaryl\$6 poly\$1para\$1xylene) same (NH3 "NH.sub.3" ammonia))) ((etch\$3 and (interlayer interlevel intermediate) and (organic teflon polyaryl\$6 poly\$1para\$1xylene) and (NH3 "NH.sub.3" ammonia) and (plasma merie RIE dry adj etch\$3)) and ((interlayer interlevel intermediate) near dielectric) not (etch\$3 same (interlayer interlevel intermediate) same (organic teflon polyaryl\$6 poly\$1para\$1xylene) same (NH3 "NH.sub.3" ammonia))) and etch\$3 same (NH3 "NH.sub.3" ammonia)) and etch\$3 with (NH3 "NH.sub.3" ammonia)) and (((etch\$3 and (interlayer interlevel intermediate) and (organic teflon polyaryl\$6 poly\$1para\$1xylene) and (NH3 "NH.sub.3" ammonia) and (plasma merie RIE dry adj etch\$3)) and ((interlayer interlevel intermediate) near insulat\$3) not (etch\$3 same (interlayer interlevel intermediate) same (organic teflon polyaryl\$6 poly\$1para\$1xylene) same (NH3 "NH.sub.3" ammonia))) ((etch\$3 and (interlayer interlevel intermediate) and (organic teflon polyaryl\$6 poly\$1para\$1xylene) and (NH3 "NH.sub.3" ammonia) and (plasma merie RIE dry adj etch\$3)) and ((interlayer interlevel intermediate) near dielectric) not (etch\$3 same (interlayer interlevel intermediate) same (organic teflon polyaryl\$6 poly\$1para\$1xylene) same (NH3 "NH.sub.3" ammonia))) and (NH3 "NH.sub.3" ammonia) with (plasma merie RIE dry adj etch\$3))) not (((etch\$3 and (interlayer interlevel intermediate) and (organic teflon polyaryl\$6 poly\$1para\$1xylene) and (NH3 "NH.sub.3" ammonia) and (plasma merie RIE dry adj etch\$3)) and ((interlayer interlevel intermediate) near insulat\$3) not (etch\$3 same (interlayer interlevel intermediate) same (organic teflon polyaryl\$6 poly\$1para\$1xylene) same (NH3 "NH.sub.3" ammonia))) ((etch\$3 and (interlayer interlevel intermediate) and (organic teflon polyaryl\$6 poly\$1para\$1xylene) and (NH3 "NH.sub.3" ammonia) and (plasma merie RIE dry adj etch\$3)) and ((interlayer interlevel intermediate) near dielectric) not (etch\$3 same (interlayer interlevel intermediate) same (organic teflon polyaryl\$6 poly\$1para\$1xylene) same (NH3 "NH.sub.3" ammonia))) and etch\$3 same (NH3 "NH.sub.3" ammonia)) and etch\$3 with (NH3 "NH.sub.3" ammonia)) and (interlayer interlevel intermediate) with (organic teflon polyaryl\$6 poly\$1para\$1xylene))</p>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/14 13:05
	25	(strip\$4 remov\$3 etch\$3 clean\$3 develop\$3 dissolv\$3) near (photoresist resist) with ((H2SO4 "H.sub.2 SO.sub.4" sulfuric) with (HF fluori?e) with (peroxide H2o2 "H.sub.2 O.sub.2"))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/27 09:33

-	64	(strip\$4 remov\$3 etch\$3 clean\$3 develop\$3 dissolv\$3) with (photoresist resist) same ((H2SO4 "H.sub.2 SO.sub.4" sulfuric) with (HF fluori?e) with (peroxide H2o2 "H.sub.2 O.sub.2"))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/27 08:45
-	39	((strip\$4 remov\$3 etch\$3 clean\$3 develop\$3 dissolv\$3) with (photoresist resist) same ((H2SO4 "H.sub.2 SO.sub.4" sulfuric) with (HF fluori?e) with (peroxide H2o2 "H.sub.2 O.sub.2"))) not ((strip\$4 remov\$3 etch\$3 clean\$3 develop\$3 dissolv\$3) near (photoresist resist) with ((H2SO4 "H.sub.2 SO.sub.4" sulfuric) with (HF fluori?e) with (peroxide H2o2 "H.sub.2 O.sub.2")))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/27 08:53
-	38	((("5266157") or ("6352937") or ("6033996") or ("5384649") or ("5584740") or ("6153484") or ("3944421") or ("4883541") or ("5300463") or ("5985125") or ("5824419") or ("5830280") or ("5250958") or ("6124211") or ("6046115") or ("6030879") or ("5776817") or ("5716495") or ("5296093"))).PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/27 08:47
-	19	((("5266157") or ("6352937") or ("6033996") or ("5384649") or ("5584740") or ("6153484") or ("3944421") or ("4883541") or ("5300463") or ("5985125") or ("5824419") or ("5830280") or ("5250958") or ("6124211") or ("6046115") or ("6030879") or ("5776817") or ("5716495") or ("5296093"))).PN.	USPAT	2004/06/27 08:47
-	58	((strip\$4 remov\$3 etch\$3 clean\$3 develop\$3 dissolv\$3) with (photoresist resist) same ((H2SO4 "H.sub.2 SO.sub.4" sulfuric) with (HF fluori?e) with (peroxide H2o2 "H.sub.2 O.sub.2"))) (((("5266157") or ("6352937") or ("6033996") or ("5384649") or ("5584740") or ("6153484") or ("3944421") or ("4883541") or ("5300463") or ("5985125") or ("5824419") or ("5830280") or ("5250958") or ("6124211") or ("6046115") or ("6030879") or ("5776817") or ("5716495") or ("5296093"))).PN.) not ((strip\$4 remov\$3 etch\$3 clean\$3 develop\$3 dissolv\$3) near (photoresist resist) with ((H2SO4 "H.sub.2 SO.sub.4" sulfuric) with (HF fluori?e) with (peroxide H2o2 "H.sub.2 O.sub.2")))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/27 09:32
-	0	20040016719.URPN.	USPAT	2004/06/27 08:49
-	10	(US-5996424-\$ or US-5266157-\$ or US-5326490-\$ or US-5185154-\$ or US-4883541-\$ or US-4585515-\$ or US-5804744-\$ or US-5863828-\$ or US-6352937-\$).did. or (JP-05013920-\$).did.	USPAT; USPAT; DERWENT	2004/06/27 09:32
-	6	(US-5605602-\$ or US-5589077-\$ or US-6225424-\$ or US-6417510-\$ or US-6509686-\$).did. or (US-20010037979-\$).did.	USPAT; US-PGPUB	2004/06/27 09:33
-	16	((US-5996424-\$ or US-5266157-\$ or US-5326490-\$ or US-5185154-\$ or US-4883541-\$ or US-4585515-\$ or US-5804744-\$ or US-5863828-\$ or US-6352937-\$).did. or (JP-05013920-\$).did.) ((US-5605602-\$ or US-5589077-\$ or US-6225424-\$ or US-6417510-\$ or US-6509686-\$).did. or (US-20010037979-\$).did.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/27 09:33
-	4	((("4370173") or ("4524125") or ("5300463") or ("5895563"))).PN.	USPAT	2004/06/27 19:03
-	0	("0618612").PN.	EPO	2004/06/27 19:03
-	2	"618612" "346668"	EPO	2004/06/27 19:21